

Data Sheet 243.95MHz SAW 3838 SPT243M3838A

V1.0

Description:

The Spectron SPT243M3838A is a SAW filter designed for applications in RF module, IOT equipments and Information& Communications filed.

The SPT243M3838A provides +10dBm power handling, low insertion loss and high out of band rejection.

The design and manufacturing of the SPT243M3838A exploit Spectron's exclusive TSAWtechnology to deliver competitive performance against state of the art at a low cost.

The SPT243M3838A is compatible with highvolume, lead-free SMT soldering processes.

Features:

- Single-Ended Input and Output
- Terminating Impedance: 50 Ω
- Environmental
 - RoHS Compliant

Specifications:

- Operation Temperature:-40°C to +85°C
- Compact miniature size
 - 3.8 mm × 3.8 mm footprint
 - 1.5mm max-height

Applications:

- RF module
- IOT equipments
- Information& Communications Devices

Electrical Specifications

Table 1 Electrical Specifications.

Item		Minimum	Typical	Maximum	Unit	
Center Frequency		fc		243.95		MHz
Insertion Loss(min)		IL		1.5	2.5	dB
Insertion Loss Fc	±110KHz	IL		1.5	3.0	dB
Passband Width @3dB			550	600		KHz
Amplitude Ripple (p-p) Fc	±110KHz	Δa		0.6	1.5	dB
Group Delay Ripple Fc	±110KHz	GDR		1.2	1.6	μs
Absolute Attenuation		a				
Fc	±600KHz		20.0	25.0		dB
Fc	±1.2MHz		35.0	40.0		dB
Fc ±	21.6MHz		50.0	55.0		dB

Note: Test Temperature: 25°C±2°C

Figure 1 Electrical Characteristics: Frequency response



SPT243.95M3838A (243.95MHz/Unbalanced/SAW)



Figure 2 Electrical Characteristics: Input return loss





Package & Dimensions^{1,2}



Pin No.	Description	
2	Input	
5	Output	
1,3,4,6	Ground	

1.All tolerances are ± 0.1 mm and the unit is mm 2.All dimensions are in millimeters.

Test circuit



Maximum Ratings

Item		Value	Unit
DC Voltage	VDC	5	V
Operation Temperature	т	-40 ~ 85	°C
Storage Temperature	Tstg	-40 ~ 85	°C
RF Power Dissipation	Р	20	dBm

Recommended SMT Solder Profile



Ordering Information

Part Number	Number of Devices	Container	
SPT243M3838A	1000pcs	Tape and Reel	

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Reliability

No.	Test item	Test condition		
1	Temperature Storage	Temperature: $85^{\circ}C\pm 2^{\circ}C$, Duration: 250h, Recovery time: 2h±0.5h (2) Temperature: $-55^{\circ}C\pm 3^{\circ}C$, Duration: 250h, Recovery time: 2h±0.5h		
2	Humidity Test	Conditions: 60°C±2°C ,90~95% RH Duration: 250h		
3	Thermal Shock	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.		
4	Vibration Fatigue	Frequency of vibration: 10~55HzAmplitude:1.5mmDirections: X,Y and ZDuration: 2h		
5	Drop Test	Cycle time: 10 times Height: 1.0m		
6	Solder Ability Test	Temperature: 245°C±5°CDuration: 3.0s5.0sDepth: DIP2/3 , SMD1/5		
7	Resistance to Soldering Heat	 (1) Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2) Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h 		

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